MA3X704 (MA704), MA3X704A (MA704A)

Silicon epitaxial planar type

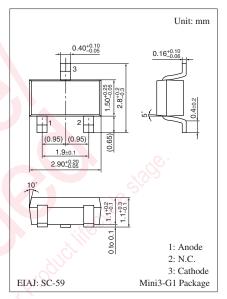
For switching For wave detection

Features

- \bullet Low forward voltage V_F and good wave detection efficiency η
- Small temperature coefficient of forward characteristic
- Small reverse current I_R

Parameter		Symbol	Rating	Unit
Reverse voltage	MA3X704	V _R	15	V
	MA3X704A		30	
Maximum peak	MA3X704	V _{RM}	15	V
reverse voltage	MA3X704A		30	
Peak forward current		I _{FM}	150	mA
Forward current		I _F	30	mA
Junction temperature		Tj	125	°C
Storage temperature		T _{stg}	-55 to +125	°C

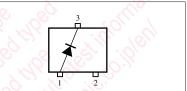
Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol

• MA3X704: M1K • MA3X704A: M1L

Internal Connection



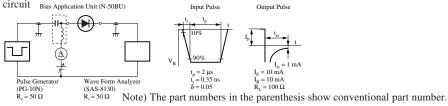
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage		V _{F1}	$I_F = 1 \text{ mA}$	- A		0.4	V
		V _{F2}	I _F = 30 mA	2.2		1.0	
Reverse current	MA3X704	I _R	V _R = 15 V			200	nA
	MA3X704A		$V_R = 30 V$			300	
Terminal capacitance		Ct	$V_R = 1 V, f = 1 MHz$		1.5		pF
Reverse recovery time *		t _{rr}	$I_F = I_R = 10 \text{ mA}$		1.0		ns
			$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency		η	$V_{IN} = 3 V_{(peak)}$, f = 30 MHz		65		%
			$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$				

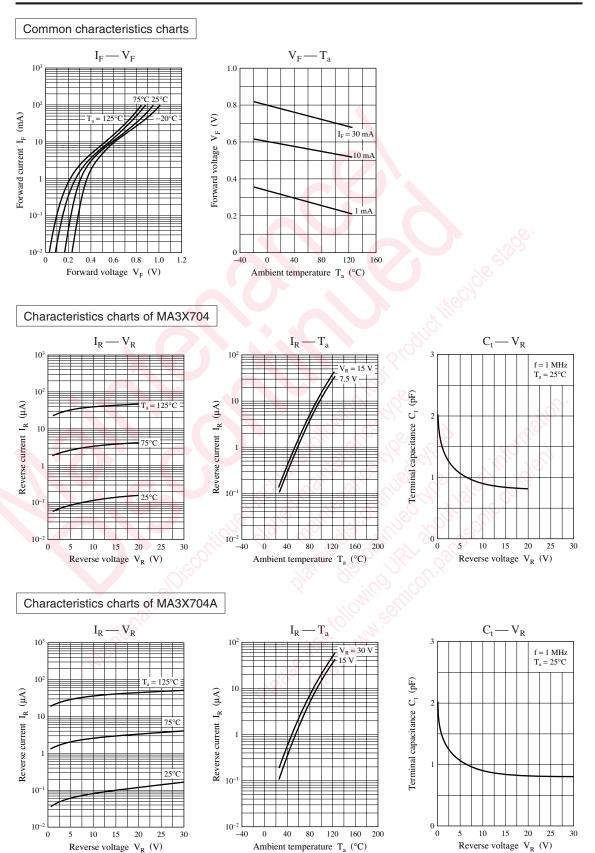
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

- 3. Absolute frequency of input and output is 2 GHz.
- 4. *: t_{rr} measurement circuit Bias Application Unit (N-50BU)



Panasonic



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